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nSiP Platform

nepes System in Package

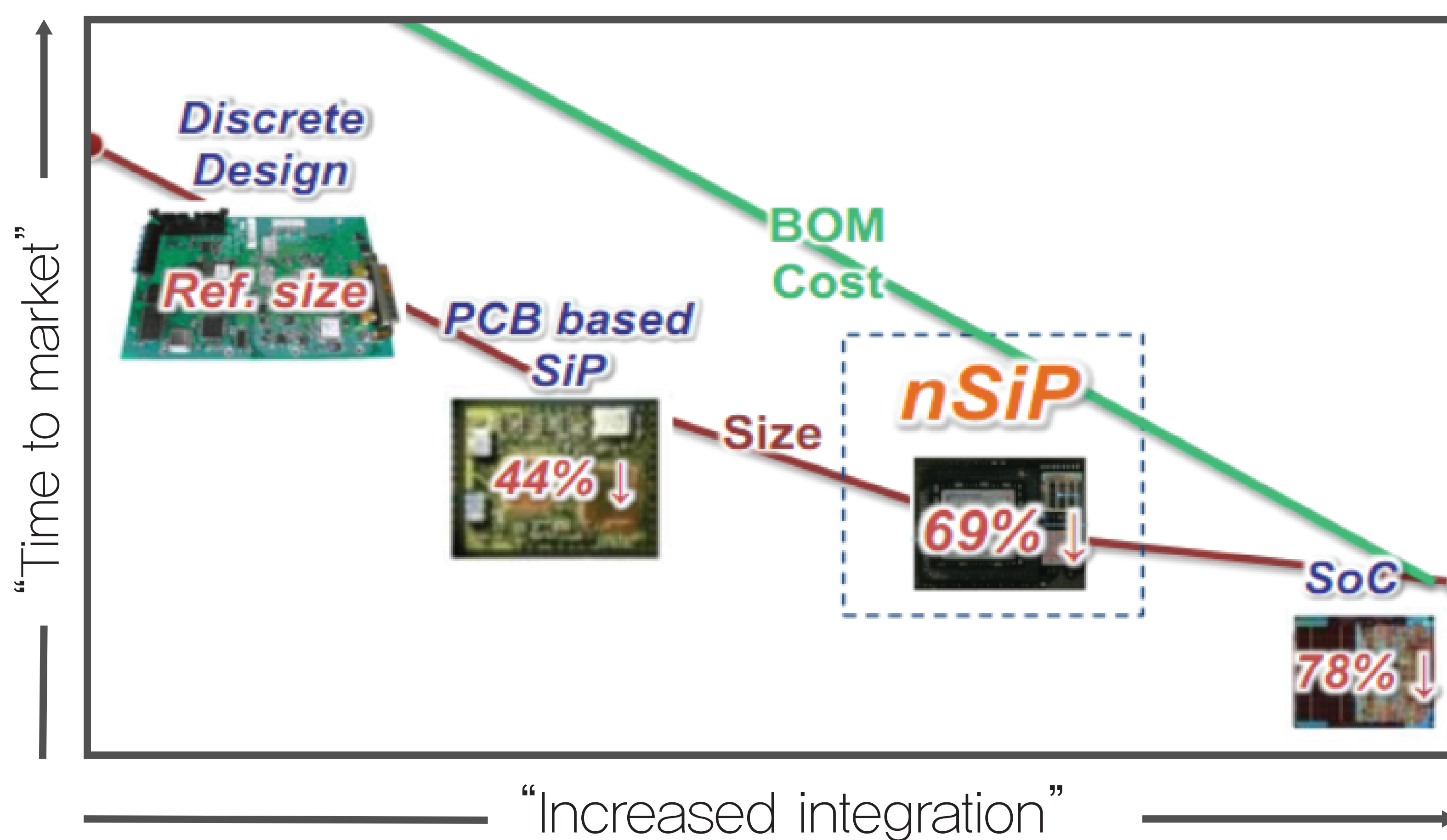
Market Drivers for semiconductor

- Smart environment at 4th industry (5G, Ai, Cloud, etc.)
- Small form factor → Heterogeneous function integration
- Rapid model change → Time to market
- Cost effective solution

What is SiP ?

- Multiple active electronic component with different functionality in a single unit
- Multiple functions associated with system or sub system
- SiP may optionally contain passive, mems sensor, optical component, and other packages and devices.
- Cost effective solution

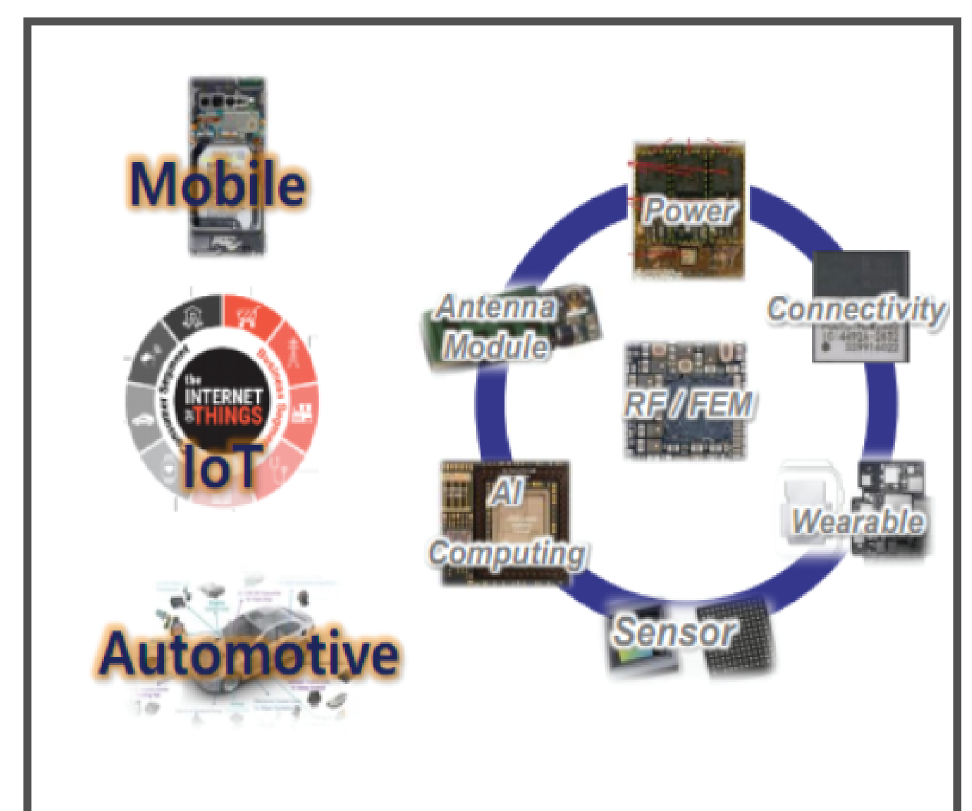
SiP (System in Package)



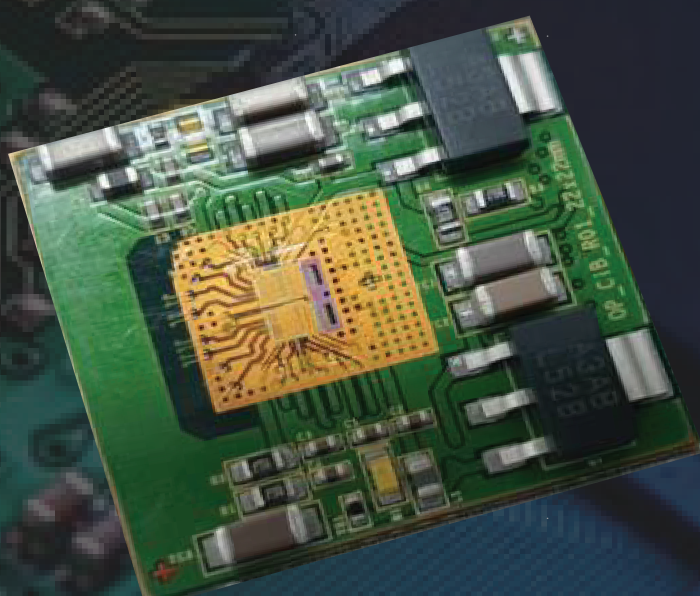
"Time to market"

"Increased integration"

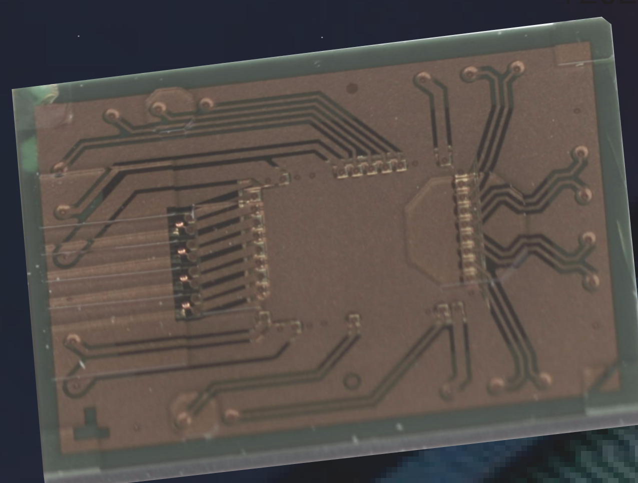
SiP Application



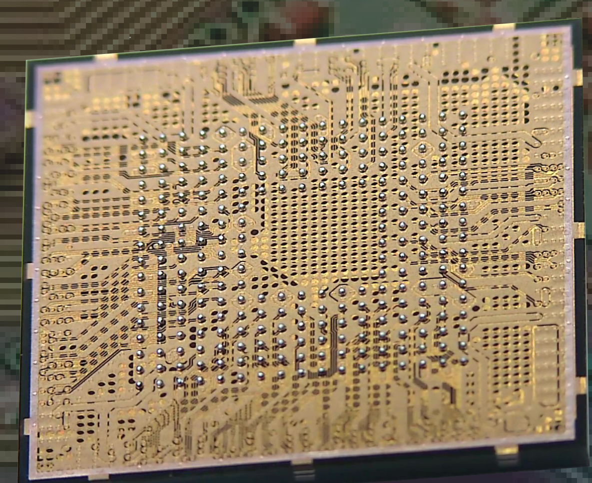
nSiP CiB (Chip in board)



nSiP Optical



nSiP Stack



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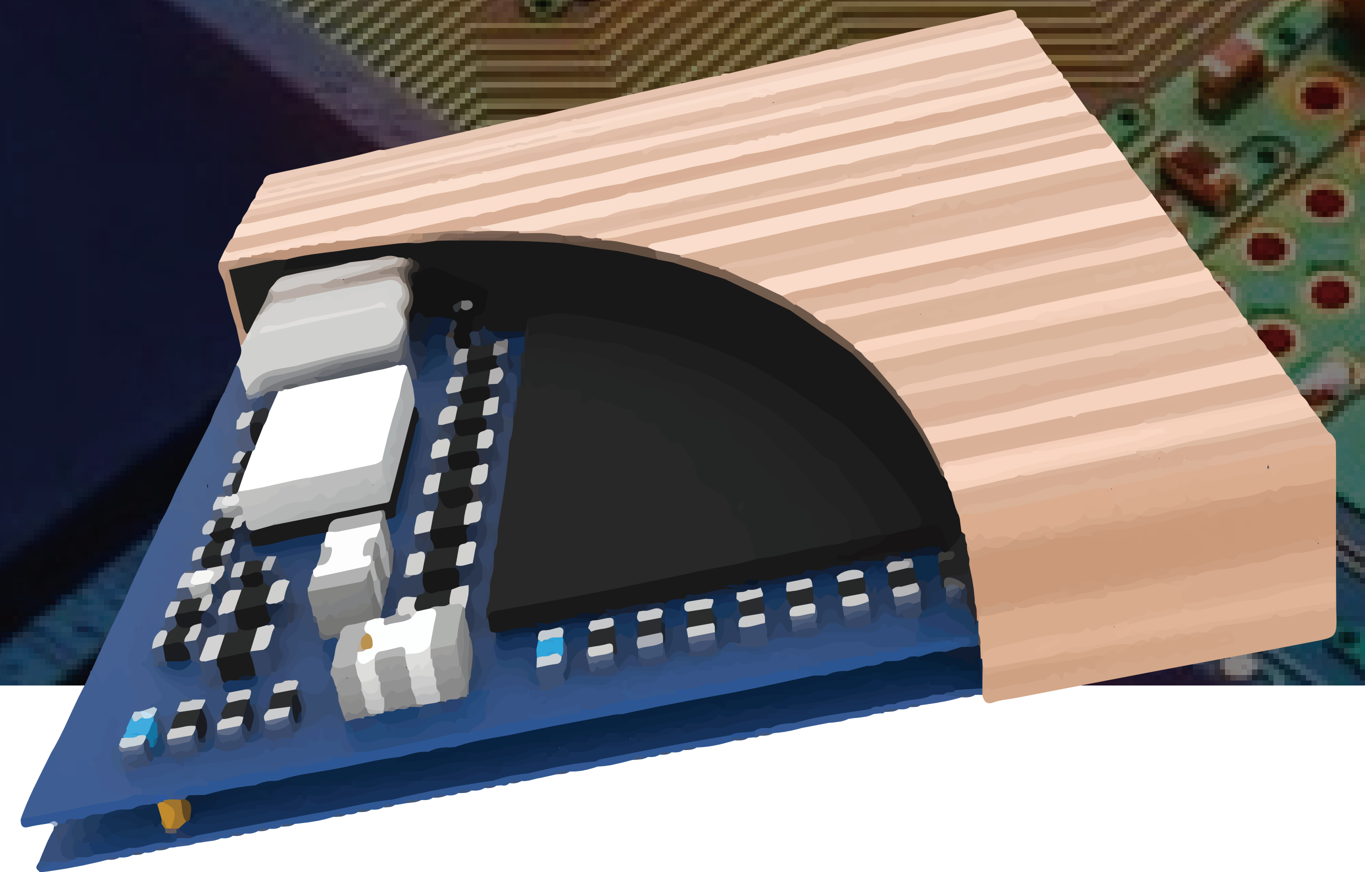
RF nSiP

nepes System in Package



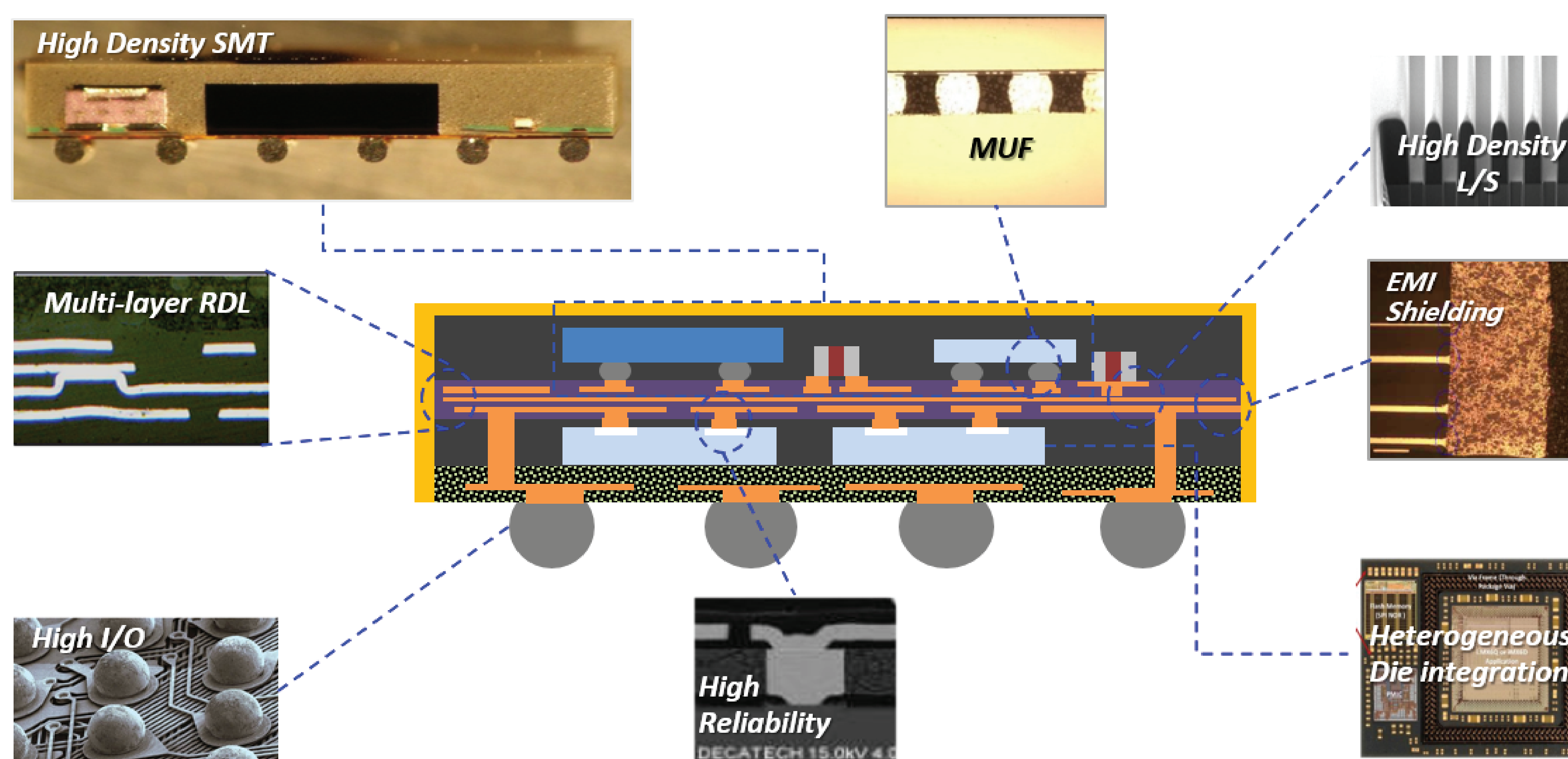
RF nSiP Platform

- Compact & Robust SiP
- High performance Embedded trace substrate (RF performance)
- Functional SiP → EMI shielding structure
- Cost effectiveness / Time to market solution
- in–line wafer (panel) level solution

nSiP Feature

- Small size and thin profile → System design flexibility
- High speed → High I/O density, Fine pitch L/S, Short interconnection path
- High power dissipation & Lower power consumption → Short thermal path

RF nSiP platform



*Cost effective wafer level batch process

Be a leader of the new era with nepes

- Total biz. solution for application & product, process, material, energy
- Advanced SiP packaging service based on semiconductor fab. capability
- Customized nSiP solution for various application and custormers

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